

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S3	3012162	noble copper silver gold platinum lead iridium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 10:19
S4	504566	nickel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/03 09:10
S5	252426	plated	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/03 09:11
S6	1134704	adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/03 09:12
S7	683734	pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/03 09:12
S8	114317	(semiconductor near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/03 09:13
S9	2118824	resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/03 09:13
S10	1209	S3 S4 S5 S6 S7 S8 S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/03 09:16

S11	148841	438/???.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/03 09:16
S12	375	S10 S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/03 09:16
S13	1511	438/118.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/03 09:16
S14	63	S10 S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/03 09:22
S15	25	(S3 S4 S5) and S6 and S7 and (S8 S9) and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2006/01/03 09:30
S16	262	(S3 S4 S5) and S6 and S7 and (S8 S9) and (257/???.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2006/01/03 09:29
S17	147	(S3 S4 S5) and S6 and S7 and (S8 S9) and (438/???.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	SAME	ON	2006/01/03 09:29
S18	68953	metal adj foil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:21

S19	690000	pad\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:21
S20	5875	S18 and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:21
S21	3015423	noble copper silver gold platinum lead iridium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/10 16:22
S22	505141	nickel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/10 16:22
S23	1517	S20 S21 S22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:23
S28	2903174	adhesive or resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:24
S29	1310	S20 S21 S22 S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:25
S30	114504	(semiconductor near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:25

S32	295	S20 S21 S22 S28 S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:27
S33	213	438/671.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:26
S34	380	438/686.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:26
S35	665	438/666.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:27
S36	866	438/652.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 16:27
S37	71	S20 S21 S22 S28 S30 438/???.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 17:13
S39	1	10/888580	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/10 17:27
S40	25	plated nickel layer.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/01/23 09:36

S41	0	plated nobel metal layer.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/01/23 09:38
S42	3	plated noble metal layer.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/01/23 09:38
S57	1019	438/113.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/30 10:41
S58	1459	438/127.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/30 10:41
S59	960	438/126.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/30 10:41
S60	911	438/460.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2006/01/30 10:42